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**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Michael GANSER et al.

Title: METHOD AND APPARATUS FOR LASER  
MICRODISSECTION

Appl. No.: 09/943,093

Appl. Filing Date: 8/31/01

Examiner: Louise Leary

Art Unit: 1654

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**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination of the present, Applicants respectfully request that the above-identified application be amended as follows:

**In the Specification:**

**On page 3, delete the last paragraph, and replace this paragraph with the following in accordance with 37 CFR §1.121. A marked up version showing changes is attached:**

*A1*  
It is a further object of the invention to provide an apparatus for laser microdissection which allows a sample field to be reliably cut out of a specimen, and which dispenses with any defocusing of the laser beam to carry off the specimen.

**On page 10, delete the first paragraph, and replace this paragraph with the following in accordance with 37 CFR §1.121. A marked up version showing changes is attached:**

*A2*  
To prepare for the cutting operation, a narrow cut width of laser beam 7 is then set. During cutting, X-Y stage 2 is then displaced in steps in such a way that laser beam 7 successively strikes the calculated reference position(s) on specimen 4, the